

Tool ID: 209
Tool Location: 107

Equipment Information Sheet
PT770 Etcher - Right Side (III-V)

Manager:
Backup:

Tom Pennell
Jeremy Clark

607-254-4309
607-254-6487

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- Chlorine and Methane chemistries used
- User must remain in the lab while tool is in operation

USAGE RESTRICTIONS

- Users must remove photoresist edge bead from full 4 inch wafers.
- pieces must be mounted to sapphire wafer.

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 15 minutes

- Maximum 4 hour block reservations anytime. Maximum 12 houres reserved in advance at any time per person. No consecutive research group reservations. Users may use any amount of unreserved time.

MATERIALS COMPATIBILITY CATEGORY

Tool Category 3: Silcion, III-V Compound Semiconductor, Glass and Metal Category	
Allowed	Not Allowed
Tool category 1/1E and 2 materials	Glass Substrates
III/V compound Semiconductors allowed	No CNF Class A or Class B metals-and oxides/compounds of i.e. (Magnesium,Zinc, Barium, Calcium)
PECVD and ALD Films	No High Vapor pressure materials
Cured organics and baked Photoresist	
Organic/Bio Materials prepped w/o Salt Buffers	

High Vapor Pressure Metals and Compoundsare materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- Photoresist, oxide, nitride, nickel masking only
- Photoresist mask - edge bead must be removed (5mm ring) if using 100mm wafers
- Limited metal masking allowed - see tool manager

Last Updated: 12/20/2022